WHAT IS CLAIMED IS:

1. A glass substrate formed by cutting at least with laser light radiation,

wherein a surface roughness of a cut side face of said glass substrate is 50 nm or less, and a depth of a laser mark on said cut side face is 0.06 nm or more.

2. The glass substrate according to claim 1, wherein said glass substrate has a strength of 45 kgf or more and 90 kgf or less based on a static load test.

3. The glass substrate according to claim 1, wherein said glass substrate has no crack and pulverized powder at said cut side face.

4. The glass substrate according to claim 1, wherein said depths of laser marks are different between on a first cut side face of said glass surface and on a second cut side face of said glass substrate, said second cut face being different from said first cut side face.

5. The glass substrate according to claim 4, wherein said depths of laser marks are different by 2% or more between on said first cut side face and on said second cut side face.

6. The glass substrate according to claim 1, wherein said laser mark is formed on a first cut side face of said glass substrate so as to have a predetermined depth from a first principal surface, whereas said laser mark is formed on a second cut side face of said glass substrate so as to have a predetermined depth from a second principal surface,

said second cut side face being different from said first cut side face and said second principal surface is the back surface of said first principal surface.

7. The glass substrate according to claim 1, wherein a thickness of said glass substrate is 0.25 mm or more and 0.7 mm or less.

8. A glass cutting method for cutting a glass plate using laser light radiation and forced cooling, wherein one of a laser power and a scanning speed of said laser light is varied between in a first cutting direction with respect to said glass plate and in a second cutting direction with respect to said glass plate, said second cutting direction being different from said first cutting direction.

9. The glass cutting method according to claim 8, wherein one of said laser power and said scanning speed of said laser light is varied by 4% or more between in said first cutting direction and in said second cutting direction.

10. A glass cutting method for cutting a glass plate using laser light radiation and forced cooling, comprising the steps of:

radiating said laser light onto a first principal surface of said glass plate so as to cut said glass plate in a first cutting direction; and

radiating said laser light onto a second principal surface of said glass plate so as to cut said glass plate in a second cutting direction, said cutting direction being different from said first cutting direction, and said second

principal surface is back surface of said first principal surface.

11. The glass cutting method according to claim 8, wherein said forced cooling is conducted by spraying any one of a volatile material and a compressed gas.

12. The glass cutting method according to claim 9, wherein said forced cooling is conducted by spraying any one of a volatile material and a compressed gas.

13. A touch panel comprising a light-transmitting conductive layer formed on a glass substrate and a film base material arranged so as to be opposed to said glass substrate with a predetermined distance therebetween, wherein

said glass substrate is formed by cutting at least with laser light radiation; and

a surface roughness of a cut side face of said glass substrate is 50 nm or less, and a depth of a laser mark on said cut side face is 0.06 mm or more.

14. The touch panel according to claim 13, wherein said depths of laser marks are different between on a first cut side face of said glass substrate and on a second cut side face of said glass substrate, said second cut side face being different from said first cut side face.

15. The touch panel according to claim 13, wherein any one of a peripheral face, a slope and a step is formed on an inner end edge of a window section of a frame on which said glass substrate of said touch panel is fixedly mounted.

16. A portable terminal including a touch panel comprising a light-transmitting conductive layer formed on a glass substrate and a film base material arranged so as to be opposed to said glass substrate with a predetermined distance therebetween, wherein

said glass substrate is formed by cutting at least with laser light radiation; and

a surface roughness of a cut side face of said glass substrate is 50 nm or less, and a depth of a laser mark on said cut side face is 0.06 mm or more.

17. The portable terminal according to claim 16, wherein said depths of laser marks are different between on a first cut side face of said glass substrate and on a second cut side face of said glass substrate, said second cut face being different from said first cut side face.